Product data sheet

1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD882 leadless ultra small Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: I_{F(AV)} ≤ 100 mA
- Reverse voltage: V_R ≤ 30 V
- Low forward voltage: V_F ≤ 450 mV
- Low reverse current: I_R ≤ 0.5 μA
- Leadless ultra small SMD plastic package
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- · Low current rectification
- · High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- · Reverse polarity protection
- Low power consumption applications

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{amb} \leq 135 °C	[1]	-	-	100	mA
		δ = 0.5; f = 20 kHz; square wave; T _{sp} \leq 145 °C		-	-	100	mA
I _R	reverse current	V _R = 10 V; T _{amb} = 25 °C		-	0.14	0.5	μΑ
V _R	reverse voltage			-	-	30	V
V _F	forward voltage	I_F = 10 mA; pulsed; $t_p \le 300$ μs; $δ \le 0.02$; T_{amb} = 25 °C		-	330	450	mV

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm².



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]		
2	Α	anode		K -} A
			Transparent top view	sym001
			DFN1006-2 (SOD882)	

^[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

Type number	Package					
	Name	Description	Version			
RB520CS30L-Q		plastic, leadless ultra small package; 2 terminals; 0.65 mm pitch; 1 mm x 0.6 mm x 0.48 mm body	SOD882			

7. Marking

Table 4. Marking codes

Type number	Marking code
RB520CS30L-Q	AP

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage			-	30	V
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{amb} \leq 135 °C	[1]	-	100	mA
		δ = 0.5; f = 20 kHz; square wave; T _{sp} ≤ 145 °C		-	100	mA
I _{FSM}	non-repetitive peak forward current	$t_p \le 8.3 \text{ ms}$; half sine wave; $T_{j(init)} = 25 \text{ °C}$		-	3	Α
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[2] [3]	-	315	mW
			[1] [3]	-	565	mW
			[3] [4]	-	865	mW
T _j	junction temperature			-	150	°C
T _{amb}	ambient temperature			-65	150	°C
T _{stg}	storage temperature			-65	150	°C

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm 2 .
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Reflow soldering is the only recommended soldering method.
- [4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2] [3]	-	-	395	K/W
			[1] [2] [4]	-	-	220	K/W
			[1] [2] [5]	-	-	145	K/W
R _{th(j-sp)}	thermal resistance from junction to solder point		[6]	-	-	70	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Reflow soldering is the only recommended soldering method.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [5] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [6] Soldering point of cathode tab.

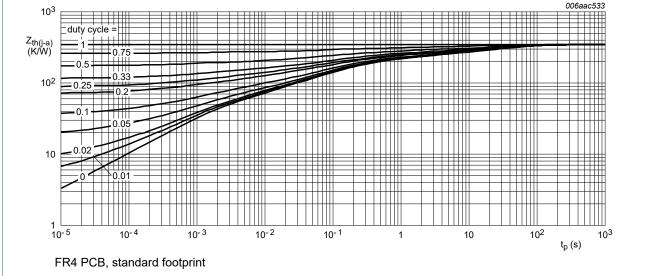


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

3 / 11

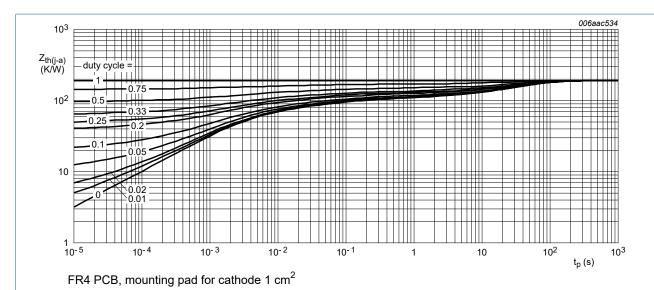
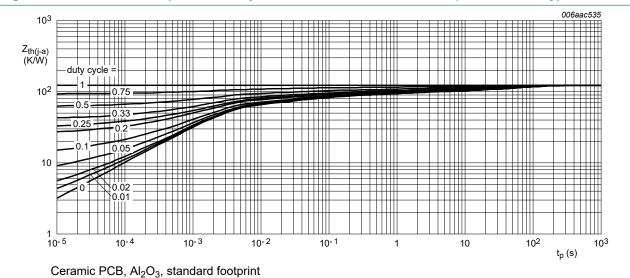


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



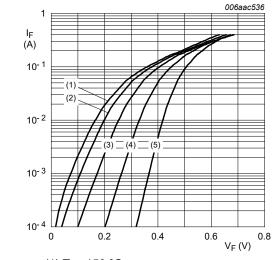
10. Characteristics

Table 7. Characteristics

Fig. 3.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _F	forward voltage	I_F = 0.1 mA; pulsed; t_p ≤ 300 μs; δ ≤ 0.02; T_{amb} = 25 °C	-	210	-	mV
		I_F = 1 A; pulsed; $t_p \le 300$ μs; $δ \le 0.02$; T_{amb} = 25 °C	-	270	-	mV
		I_F = 10 mA; pulsed; $t_p \le 300$ μs; $δ \le 0.02$; T_{amb} = 25 °C	-	330	450	mV
		I_F = 100 mA; pulsed; t_p ≤ 300 μs; δ ≤ 0.02; T_{amb} = 25 °C	-	450	-	mV
I _R	reverse current	V _R = 10 V; T _{amb} = 25 °C	-	0.14	0.5	μΑ
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _{amb} = 25 °C	-	10	-	pF

Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



(1) $T_i = 150 \, ^{\circ}C$

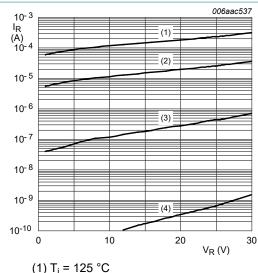
 $(2) T_i = 125 °C$

 $(3) T_i = 85 ^{\circ}C$

 $(4) T_i = 25 ^{\circ}C$

 $(5) T_i = -40 ^{\circ}C$

Fig. 4. Forward current as a function of forward voltage; typical values

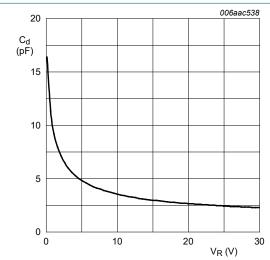


(1) $T_j = 125 \,^{\circ}\text{C}$ (2) $T_j = 85 \,^{\circ}\text{C}$

 $(3) T_i = 25 ^{\circ}C$

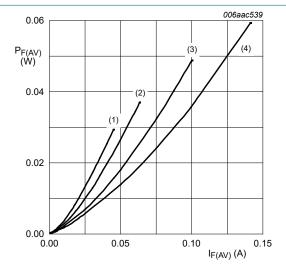
(4) $T_j = -40 \, ^{\circ}C$

Fig. 5. Reverse current as a function of reverse voltage; typical values



 $f = 1 \text{ MHz}; T_{amb} = 25 \text{ °C}$

Fig. 6. Diode capacitance as a function of reverse voltage; typical values



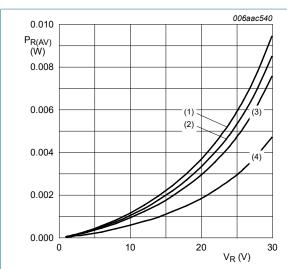
T_i = 150 °C

 $(1) \delta = 0.1$

 $(2) \delta = 0.2$

 $(3) \delta = 0.5$ $(4) \delta = 1$

Fig. 7. Average forward power dissipation as a function of average forward current; typical values



T_j = 125 °C

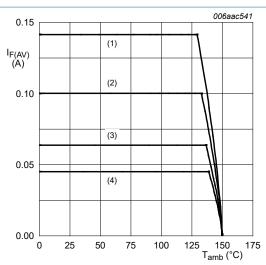
 $(1) \delta = 1$; DC

(2) $\delta = 0.9$; f = 20 kHz

(3) $\delta = 0.8$; f = 20 kHz

 $(4) \delta = 0.5$; f = 20 kHz

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T_i = 150 °C

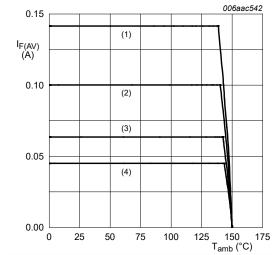
 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²

T_i = 150 °C

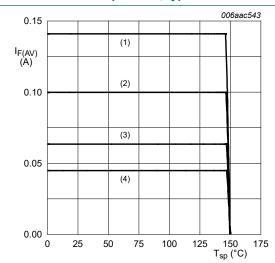
 $(1) \delta = 1$; DC

 $(2) \delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 10. Average forward current as a function of ambient temperature; typical values



 $T_i = 150 \,{}^{\circ}\text{C}$

 $(1) \delta = 1; DC$

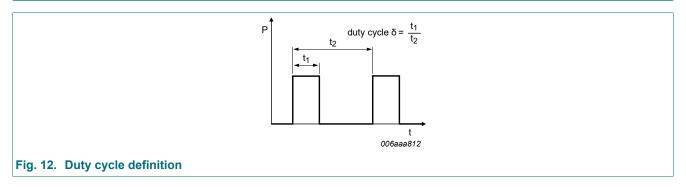
(2) δ = 0.5; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 11. Average forward current as a function of solder point temperature; typical values

11. Test information



The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

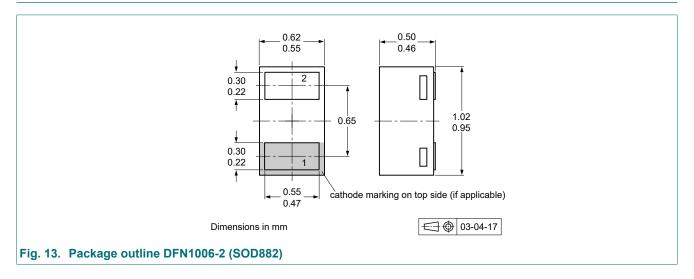
 $I_{RMS}=I_{F(AV)}$ at DC

 I_{RMS} = I_{M} × $\sqrt{\delta}$ with I_{RMS} defined as RMS current

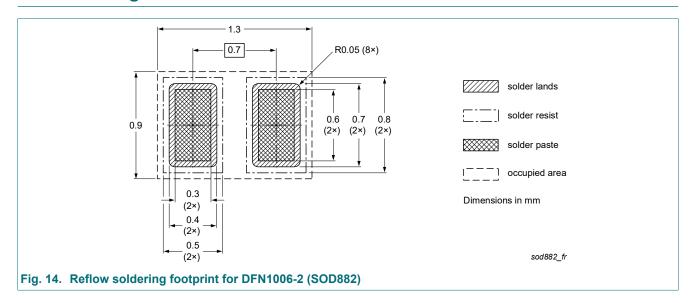
Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline



13. Soldering



14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
RB520CS30L-Q v.1	20250429	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
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Product data sheet

Contents

1.	General description	1
2.	Features and benefits	1
3.	Applications	. 1
4.	Quick reference data	1
5.	Pinning information	2
6.	Ordering information	2
7.	Marking	2
8.	Limiting values	. 2
9.	Thermal characteristics	. 3
10.	Characteristics	4
11.	Test information	7
12.	Package outline	7
13.	Soldering	8
14.	. Revision history	9
15.	Legal information	10

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